Final Product Change Notification

201406006F03

Issue Date: 18-Feb-2015
Effective Date: 08-Jun-2015

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Change Category

[ ] Wafer Fab process
[ ] Wafer Fab materials
[X] Wafer Fab location
[ ] Assembly Process
[X] Assembly Materials
[ ] Assembly Location
[ ] Product Marking
[ ] Electrical spec./Test coverage
[ ] Test Location
[ ] Design
[ ] Mechanical Specification
[ ] Packing/Shipping/Labeling

Introduce Manchester UK as a source for T6 Trench MOS Auto products

Details of this Change

The Trench 6 Automotive TrenchMOS silicon diffusion process sourced from Global Foundries, Singapore, has been qualified to AEC-Q101 in the NXP Manchester UK Fab.

NXP also intends to incorporate Jihlin as an alternate lead frame material supplier for TO-220AB (SOT78). Jihlin are a known trusted supplier, currently qualified for the Standard MOS and LFPAK Leadframe configurations. NXP will continue to use SDI and Possehl. The package outline remains within the current package outline drawing (POD), but there will be physical changes to the shoulders of the Leads in order to bring an advantage of improved RDS(on) performance.

Please refer to attached file for full change details

Why do we Implement this Change

Further to the introduction of dual source supply of Trench 6 Standard MOS products from Singapore and Manchester, NXP is now extending this sourcing capability to the latest Trench 6 designs for Automotive products. Moreover Jihlin will be introduced as an alternate Leadframe material supplier for TO-220AB (SOT78) T6 types to further enhance the PPM level, provide the highest reliability, and lowest risk of Incidents.

Identification of Affected Products

Top side marking

Manchester diffused product will be identifiable with the inclusion of the letter 'E' on the top side marking of the product, and the box labels will state 'Diffused in EU'

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 08-Jun-2015

Impact

no impact to the product's functionality anticipated.
- The finished products will be electrically equivalent on all parameters, both static and dynamic.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

N/A

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 20-Mar-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:
e-mail address powermos.pcn@nxp.com
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Changed Orderable Part#	Customer Part#	Changed Part 12NC
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BUK755R4-100E,127	BUK755R4-100E,127	934066483127
BUK751R8-40E,127	BUK751R8-40E,127	934066479127